

CLAIMS

1. A polyamide resin composition which comprises 30 to 80% by mass of a polyamide resin (A) comprising (i) a
5 dicarboxylic acid component unit (a-1) consisting of 30 to 100 mol% of a dicarboxylic acid component unit derived from terephthalic acid, 0 to 70 mol% of an aromatic dicarboxylic acid component unit other than the terephthalic acid, and/or 0 to 70 mol% of an aliphatic dicarboxylic acid component
10 unit having 4 to 20 carbon atoms (provided that the total amount of these dicarboxylic acid component units is 100 mol%) and (ii) 100 mol% of a diamine component unit (a-2) consisting of a straight chain aliphatic diamine component unit having 4 to 20 carbon atoms and/or a branched chain
15 aliphatic diamine component unit having 4 to 20 carbon atoms, as a diamine component unit; 10 to 60% by mass of an inorganic filler (B); and 5 to 50% by mass of a white pigment (C), wherein a molded product that is injection molded from the polyamide resin composition has a flexural
20 modulus of elasticity at 130°C of 4500 MPa to 12000 MPa.

2. A polyamide resin composition which comprises 30 to 80% by mass of a polyamide resin (A) comprising (i) a dicarboxylic acid component unit (a-1) consisting of 30 to

100 mol% of a dicarboxylic acid component unit derived from terephthalic acid, 0 to 70 mol% of an aromatic dicarboxylic acid component unit other than the terephthalic acid, and/or 0 to 70 mol% of an aliphatic dicarboxylic acid component
5 unit having 4 to 20 carbon atoms (provided that the total amount of these dicarboxylic acid component units is 100 mol%) and (ii) 100 mol% of a diamine component unit (a-2) consisting of a straight chain aliphatic diamine component unit having 4 to 20 carbon atoms and/or a branched chain
10 aliphatic diamine component unit having 4 to 20 carbon atoms, as a diamine component unit; 10 to 60% by mass of an inorganic filler (B); and 5 to 50% by mass of a white pigment (C), wherein the polyamide resin composition further comprises an ultraviolet absorber (D) having a heating mass
15 reduction ratio of 50% by mass or less when held at 340°C for 10 minutes under a nitrogen atmosphere, or both an ultraviolet absorber (D) and a hindered amine compound (E).

3. The polyamide resin composition according to claim 2,
20 wherein the ultraviolet absorber (D) is one or more compounds selected from a benzotriazole compound, a triazine compound or a benzophenone compound.

4. The polyamide resin composition according to claims 1

to 3, wherein the polyamide resin (A) has an intrinsic viscosity $[\eta]$ of 0.5 to 0.9 dl/g and a melting point of 260 to 350°C.

5 5. The polyamide resin composition according to claims 1 to 3, wherein the diamine component unit (a-2) of the polyamide resin (A) comprises one or more kinds selected from 1,6-diaminohexane, 1,10-diaminodecane, 1,11-diaminoundecane and 1,12-diaminododecane.

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6. The polyamide resin composition according to claims 1 to 3, wherein the inorganic filler (B) is glass fiber.

7. The polyamide resin composition according to claims 1
15 to 3, wherein the white pigment (C) is titanium oxide.

8. A reflector plate which is formed from the polyamide resin composition according to claims 1 to 3.

20 9. A reflector plate for a light emitting diode device, which is formed from the polyamide resin composition according to claims 1 to 3.

10. The reflector plate for a light emitting diode

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according to claim 9, wherein reflectance retention is 80% or more.